



**NOTES:**

- 1- CHAIN CUTOFF: 'B' DIMENSION PLUS (0.25) / .010.
- 2- THIS ASSEMBLY MUST CONFORM TO PRODUCT SPECIFICATION NO. 7660.
- 3- THIS ASSEMBLY WILL ACCOMMODATE #24 Gg. SOLID WIRE WITH A MAXIMUM INSULATION DIAMETER OF (1.57) / .062.
- 4- PARTS SHIPPED TO THE CUSTOMER IN CHAINS BUT ORDERED AND PRICED IN DISCRETE PARTS.
- 5- FINISH: SEE SDES-88  
 (102) OVERALL TIN: .00508 MICROMETERS MIN OVER .00254 MICROMETERS MIN COPPER.  
 (P909) \*OVERALL HOT TIN DIP: .00254 MICROMETERS MIN.  
 \*THE PRIMARY SHIPPING CARTON WILL BE LABELED 'COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'. CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN/LEAD PLATINGS.

NO. OF HOUSINGS IN CHAIN	CIRCUIT SIZE	DIM. "A"	DIM. "B"	CIRCUIT SIZE	DIM. "A"	DIM. "B"	NO. OF HOUSINGS IN CHAIN
8	2	(3.96±.15) .156±.006	(8.38±.18) .330±.007	10	(35.66±.25) 1.404±.010	(40.08±.25) 1.578±.010	2
6	3	(7.92±.15) .312±.006	(12.34±.18) .486±.007	11	(39.62±.25) 1.560±.010	(44.04±.25) 1.734±.010	2
5	4	(11.89±.15) .468±.006	(16.31±.18) .642±.007				
4	5	(15.85±.18) .624±.007	(20.27±.20) .798±.008				
3	6	(19.81±.18) .780±.007	(24.23±.20) .954±.008				
3	7	(23.77±.18) .936±.007	(28.19±.23) 1.110±.009				
2	8	(27.74±.20) 1.092±.008	(32.16±.23) 1.266±.009				
2	9	(31.70±.20) 1.248±.008	(36.12±.23) 1.422±.009				

W	CHG. TO LEAD FREE LCP2004-1996 4-13-04 SCHAEFER
T	REVISED PER ECR US 0872 9-20-08 JUS
W	REDRAWN ECL-8778 0808 2/14/86
W	REV. LTR. REVISIONS

REVISIONS ONLY ON CAD SYSTEM

CONNECTOR ASSEMBLY  
 KK (3.96) / .156 CENTER  
 INSULATION DISPLACEMENT

MOLEX INCORPORATED  
 1500 W. 15TH AVENUE  
 P.O. BOX 100  
 BERKELEY, CA 94701

DATE: 10/11/04  
 DRAWN: JUS  
 CHECKED: JUS  
 APPROVED: JUS

SEE CHART SDA-40785-R\*J

SCALE: 4:1

